SCLS400G - APRIL 1998 - REVISED APRIL 2005

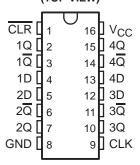
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- Contain Four Flip-Flops With Double-Rail Outputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

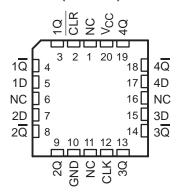
The 'LV175A devices are quadruple D-type flip-flops designed for 2-V to 5.5-V V_{CC} operation.

These devices have a direct clear (CLR) input and feature complementary outputs from each flip-flop.

SN54LV175A . . . J OR W PACKAGE SN74LV175A . . . D, DB, DGV, NS, OR PW PACKAGE (TOP VIEW)



SN54LV175A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 B	Tube of 40	SN74LV175AD	11/4754
	SOIC - D	Reel of 2500	SN74LV175ADR	LV175A
	SOP - NS	Reel of 2000	SN74LV175ANSR	74LV175A
4000 1- 0500	SSOP – DB	Reel of 2000	SN74LV175ADBR	LV175A
–40°C to 85°C		Tube of 90	SN74LV175APW	
	TSSOP - PW	Reel of 2000	SN74LV175APWR	LV175A
		Reel of 250	SN74LV175APWT	
	TVSOP - DGV	Reel of 2000	SN74LV175ADGVR	LV175A
	CDIP – J	Tube of 25	SNJ54LV175AJ	SNJ54LV175AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV175AW	SNJ54LV175AW
	LCCC - FK	Tube of 55	SNJ54LV175AFK	SNJ54LV175AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCLS400G - APRIL 1998 - REVISED APRIL 2005

description/ordering information (continued)

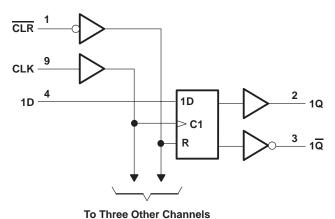
Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse.

Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

FUNCTION TABLE (each flip-flop)

	INPUTS		OUTI	PUTS
CLR	CLK	Q	Q	
L	Х	Χ	L	Н
Н	\uparrow	Н	Н	L
Н	\uparrow	L	L	Н
Н	L	Χ	Q_0	\overline{Q}_0

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.



SN54LV175A, SN74LV175A QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

SCLS400G - APRIL 1998 - REVISED APRIL 2005

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Voltage range applied to any output in the high	n-impedance	
or power-off state, V _O (see Note 1)		0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)		
Input clamp current, I_{IK} ($V_I < 0$)		–20 mA
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		
Package thermal impedance, θ _{JA} (see Note 3)		
,	DB package	
	DGV package	
	NS package	
	PW package	
Storage temperature range, T _{stg}	. •	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54LV175A, SN74LV175A QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

SCLS400G - APRIL 1998 - REVISED APRIL 2005

recommended operating conditions (see Note 4)

			SN54L	.V175A	SN74L	.V175A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
Maria	High lavelingut vallage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		$V_{CC} = 2 V$		0.5		0.5	
V	Low lovel input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
V _{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		V _{CC} ×0.3		$V_{CC} \times 0.3$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
VI	Input voltage		0	5.5	0	5.5	V
Vo	Output voltage		0 ,	V _{CC}	0	VCC	V
		V _{CC} = 2 V	S	-50		-50	μΑ
	High level output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	90	-2		-2	
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$	Q	-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		$V_{CC} = 2 V$		50		50	μΑ
	Lauria and autout aumant	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		20	
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPITIONS	.,	SN54	LV175A		SN74	LV175A		LINUT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
N	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V
VOH	I _{OH} = -6 mA	3 V	2.48			2.48			V
	I _{OH} = -12 mA	4.5 V	3.8	141		3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		KEL	0.1			0.1	
M	I _{OL} = 2 mA	2.3 V		Q	0.4			0.4	V
VOL	I _{OL} = 6 mA	3 V	9	5	0.44			0.44	V
	I _{OL} = 12 mA	4.5 V	² QC		0.55			0.55	
lį	V _I = 5.5 V or GND	0 to 5.5 V	N. O		±1			±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20			20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			5			5	μΑ
C _i	$V_I = V_{CC}$ or GND	3.3 V		1.4			1.4		pF



SCLS400G - APRIL 1998 - REVISED APRIL 2005

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			$T_A = 1$	25°C	SN54L	/175A	SN74L	/175A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Pulse direction	CLR low	6		6		6		
t _W	Pulse duration	CLK high or low	6.5		7	10,01	7		ns
	Output the a hadron OUKA	Data	7		7.5	M	7.5		
t _{su}	Setup time before CLK↑	CLR inactive	7		7.5		7.5		ns
th	Hold time, data after CLK↑		0.5		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 1$	25°C	SN54L	√175A	SN74L	/175A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
Ţ.	Poles desettes	CLR low	5		5		5		
t _W	Pulse duration	CLK high or low	5		5	N.C.	5		ns
	Outure the end of the OUT	Data	5		5	MIL	5		
t _{su}	Setup time before CLK↑	CLR inactive	5		5		5		ns
th	Hold time, data after CLK↑		1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			$T_A = 1$	25°C	SN54L	/175A	SN74L	/175A	LINUT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas dimetias	CLR low	5		5		5		
t _W	Pulse duration	CLK high or low	5		5	10,01	5		ns
	Outure the hadene OUKA	Data	4		4	M	4		
t _{su}	Setup time before CLK↑	CLR inactive	5		5		5		ns
t _h	Hold time, data after CLK↑		1		1		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

242445	FROM	то	LOAD	T,	_Δ = 25°C	;	SN54L\	/175A	SN74L	/175A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	50*	105*		45*	2	45		N 41 1-
^f max			C _L = 50 pF	40	80		35	1/4	35		MHz
4	CLR	Any	0. 45.5		7.9*	16.6*	1*	20*	1	20	
^t pd	CLK	Any	$C_L = 15 pF$		9.3*	18.8*	1*,	22*	1	22	ns
	CLR	Any	0 50 5		10.4	21.6	4)	25.5	1	25.5	
^t pd	CLK	Any	$C_L = 50 pF$		12	23.3	01	27	1	27	ns
tsk(o)			C _L = 50 pF			2	2			2	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



SN54LV175A, SN74LV175A QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

SCLS400G - APRIL 1998 - REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T,	Վ = 25° C	;	SN54L	V175A	SN74L\	√175A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	90*	155*		75*	4	75		N41.1-
f _{max}			C _L = 50 pF	50	120		45	14	45		MHz
4 .	CLR	Any	0: 45.5		5.5*	10.1*	1*	12*	1	12	
^t pd	CLK	Any	$C_L = 15 pF$		6.5*	11.5*	1*,	13.5*	1	13.5	ns
	CLR	Any	0 50 5		7.4	13.6	3	15.5	1	15.5	
^t pd	CLK	Any	C _L = 50 pF		8.4	15	01	17	1	17	ns
tsk(o)			C _L = 50 pF			1.5	y _q			1.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	_A = 25°C	;	SN54L	/175A	SN74L	√175A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
4			C _L = 15 pF	150*	215*		125*	4	125		NAL I—
f _{max}			C _L = 50 pF	85	165		75	1/6	75		MHz
	CLR	Any	0 45 5		3.7*	6.4*	1*	7.5*	1	7.5	
^t pd	CLK	Any	C _L = 15 pF		4.6*	7.3*	1*,	8.5*	1	8.5	ns
	CLR	Any	0 50 5		5.3	8.4	4 9	9.5	1	9.5	
^t pd	CLK	Any	$C_L = 50 pF$		6	9.3	01	10.5	1	10.5	ns
^t sk(o)			C _L = 50 pF			1	y _Q			1	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 5)

	DADAMETED	SN	74LV175	iΑ	
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.3	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic VOH		3		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

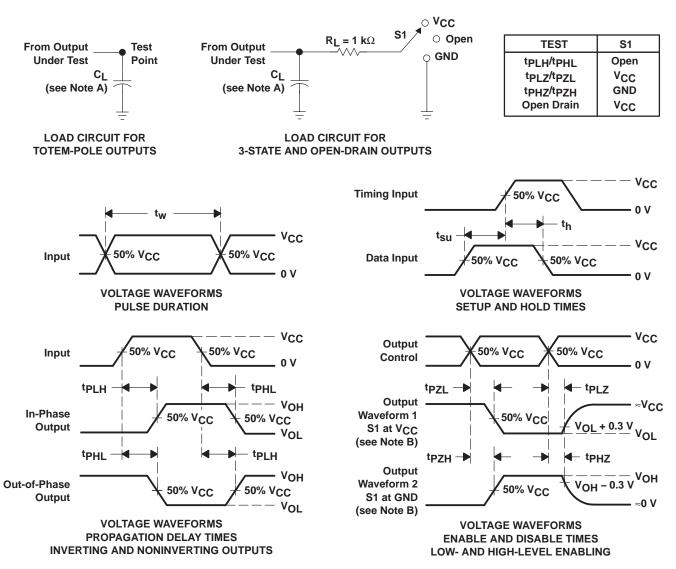
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS		VCC	TYP	UNIT
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 10 MHz	3.3 V	13.6	pF
				5 V	14.5	



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzi and tpzH are the same as ten.
 - G. tpHL and tpLH are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV175AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV175APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

6-Dec-2006

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

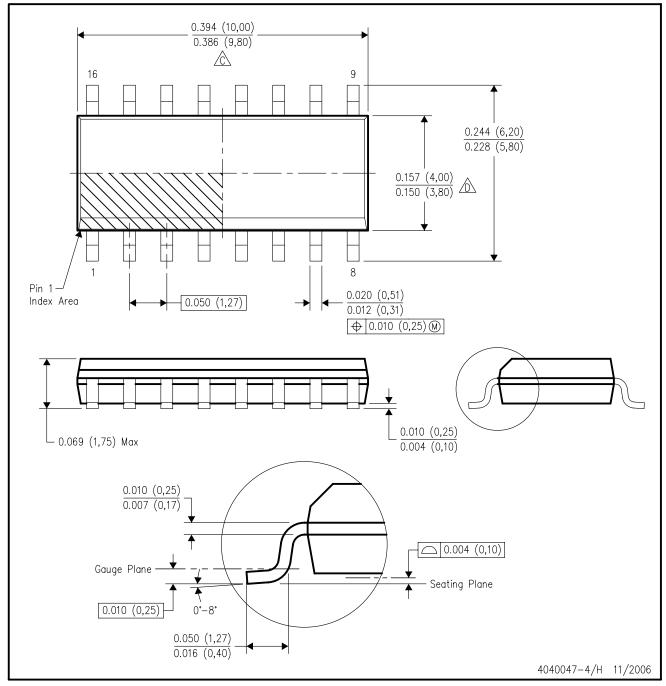
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2006, Texas Instruments Incorporated